

Rochester Electronics Manufactured Components

Rochester branded components are manufactured using either die/wafers purchased from the original suppliers or Rochester wafers recreated from the original IP. All recreations are done with the approval of the OCM.

Parts are tested using original factory test programs or Rochester developed test solutions to guarantee product meets or exceed the OCM data sheet.

Quality Overview

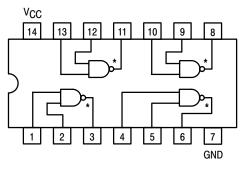
- ISO-9001
- AS9120 certification
- Qualified Manufacturers List (QML) MIL-PRF-35835
 - Class Q Military
 - Class V Space Level
- Qualified Suppliers List of Distributors (QSLD)

• Rochester is a critical supplier to DLA and meets all industry and DLA standards.

Rochester Electronics, LLC is committed to supplying products that satisfy customer expectations for quality and are equal to those originally supplied by industry manufacturers.

The original manufacturer's datasheet accompanying this document reflects the performance and specifications of the Rochester manufactured version of this device. Rochester Electronics guarantees the performance of its semiconductor products to the original OEM specifications. 'Typical' values are for reference purposes only. Certain minimum or maximum ratings may be based on product characterization, design, simulation, or sample testing.

Quad 2-Input NAND Buffer



***OPEN COLLECTOR OUTPUTS**

GUARANTEED OPERATING RANGES

Symbol	Parameter	Min	Тур	Max	Unit
VCC	Supply Voltage	4.75	5.0	5.25	V
TA	Operating Ambient Temperature Range	0	25	70	°C
VOH	Output Voltage – High			5.5	V
IOL	Output Current – Low			24	mA



ON Semiconductor[™]

http://onsemi.com

LOW POWER SCHOTTKY



PLASTIC N SUFFIX CASE 646



SOIC D SUFFIX CASE 751A



SOEIAJ M SUFFIX CASE 965

ORDERING INFORMATION

Device	Package	Shipping	
SN74LS38N 14 Pin DIP 2		2000 Units/Box	
SN74LS38D	SOIC-14	55 Units/Rail	
SN74LS38DR2	SOIC-14	2500/Tape & Reel	
SN74LS38M	SOEIAJ-14	See Note 1	
SN74LS38MEL	SOEIAJ-14	See Note 1	

 For ordering information on the EIAJ version of the SOIC package, please contact your local ON Semiconductor representative.

SN74LS38

		Limits					
Symbol	Parameter	Min	Тур	Max	Unit	Test Co	onditions
VIH	Input HIGH Voltage	2.0			V	Guaranteed Input HIGH Voltage for All Inputs	
VIL	Input LOW Voltage			0.8	V	Guaranteed Input LOW Voltage for All Inputs	
VIK	Input Clamp Diode Voltage		-0.65	-1.5	V	$V_{CC} = MIN, I_{IN} = -18 \text{ mA}$	
ЮН	Output HIGH Current			250	μΑ	$V_{CC} = MIN, V_{OH} = MAX$	
Ve	Output LOW Voltage		0.25	0.4	V	$I_{OL} = 12 \text{ mA}$ $V_{CC} = V_{CC} \text{ MII}$	
VOL			0.35	0.5	V	I _{OL} = 24 mA	V _{IN} = V _{IL} or V _{IH} per Truth Table
				20	μΑ	$V_{CC} = MAX, V_{IN} = 2.4 V$ $V_{CC} = MAX, V_{IN} = 7.0 V$	
ΊΗ	Input HIGH Current			0.1	mA		
۱ _{IL}	Input LOW Current			-0.4	mA	$V_{CC} = MAX, V_{IN} = 0.4 V$	
ICC	Power Supply Current Total, Output HIGH			2.0	mA	nA V _{CC} = MAX	
	Total, Output LOW			12			

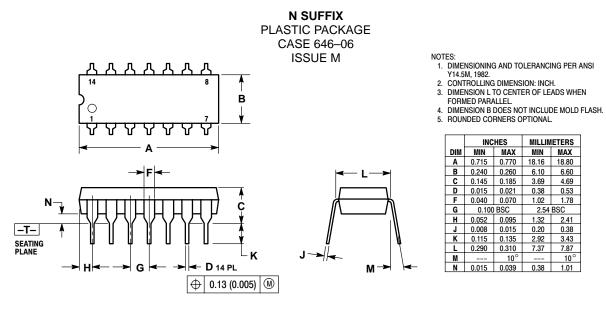
DC CHARACTERISTICS OVER OPERATING TEMPERATURE RANGE (unless otherwise specified)

AC CHARACTERISTICS ($T_A = 25^{\circ}C$)

		Limits		Limits			
Symbol	Parameter	Min	Тур	Max	Unit	Test Conditions	
^t PLH	Turn-Off Delay, Input to Output		20	32	ns	V_{CC} = 5.0 V, R _L = 667 Ω	
^t PHL	Turn-On Delay, Input to Output		18	28	ns	$C_L = 45 \text{ pF}$	

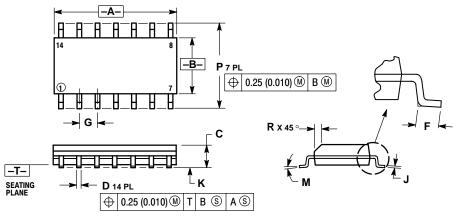
SN74LS38

PACKAGE DIMENSIONS



	INC	HES	MILLIN	IETERS	
DIM	MIN MAX		MIN	MAX	
Α	0.715	0.770	18.16	18.80	
В	0.240	0.260	6.10	6.60	
С	0.145	0.185	3.69	4.69	
D	0.015	0.021	0.38	0.53	
F	0.040	0.070	1.02	1.78	
G	0.100 BSC		2.54 BSC		
н	0.052	0.095	1.32	2.41	
J	0.008	0.015	0.20	0.38	
K	0.115	0.135	2.92	3.43	
L	0.290	0.310	7.37	7.87	
М		10°		10°	
Ν	0.015	0.039	0.38	1.01	

D SUFFIX PLASTIC SOIC PACKAGE CASE 751A-03 ISSUE F



NOTES:

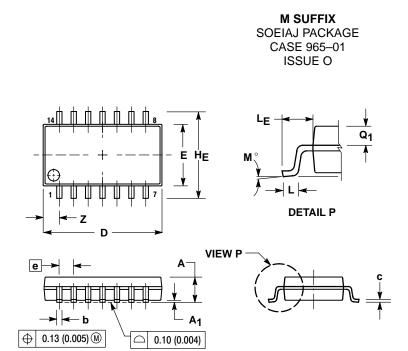
DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
CONTROLLING DIMENSION: MILLIMETER.

3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.

MOLD PROTRUSION. 4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE. 5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIN	IETERS	INC	HES			
DIM	MIN	MAX	MIN	MAX			
Α	8.55	8.75	0.337	0.344			
В	3.80	4.00	0.150	0.157			
С	1.35	1.75	0.054	0.068			
D	0.35	0.49	0.014	0.019			
F	0.40	1.25	0.016	0.049			
G	1.27	1.27 BSC		BSC			
J	0.19	0.25	0.008	0.009			
K	0.10	0.25	0.004	0.009			
М	0 °	7°	0 °	7°			
Р	5.80	6.20	0.228	0.244			
R	0.25	0.50	0.010	0.019			

PACKAGE DIMENSIONS



- NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. CONTROLLING DIMENSION: MILLIMETER.
- 2 3. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS AND ARE MEASURED AT THE PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
- 4.
- TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY. THE LEAD WIDTH DIMENSION (b) DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE 5. DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 (0.018).

	MILLIN	IETERS	INCHES		
DIM	MIN	MAX	MIN	MAX	
Α		2.05		0.081	
A ₁	0.05	0.20	0.002	0.008	
b	0.35	0.50	0.014	0.020	
c	0.18	0.27	0.007	0.011	
D	9.90	10.50	0.390	0.413	
Е	5.10	5.45	0.201	0.215	
е	1.27 BSC		0.050 BSC		
Η _E	7.40	8.20	0.291	0.323	
0.50	0.50	0.85	0.020	0.033	
LE	1.10	1.50	0.043	0.059	
Μ	0 °	10 °	0 °	10 °	
Q ₁	0.70	0.90	0.028	0.035	
Z		1.42		0.056	

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